WAFER DIVIDING METHOD

Abstract of the Disclosure

A wafer dividing method for dividing a wafer along a first set of plural streets extending parallel to each other, and a second set of plural streets extending parallel to each other and extending perpendicularly to the first set of the streets, the wafer having a plurality of rectangular regions defined on the face thereof by these streets. The wafer dividing method includes a groove forming step of forming grooves along the streets on the face of the wafer, and a grinding step of grinding the back of the wafer after the groove forming step. The grooves formed by the groove forming step include grooves having a first depth D1, and grooves having a second depth D2 which is greater than the first depth D1 (D2 > D1).

Figure 7